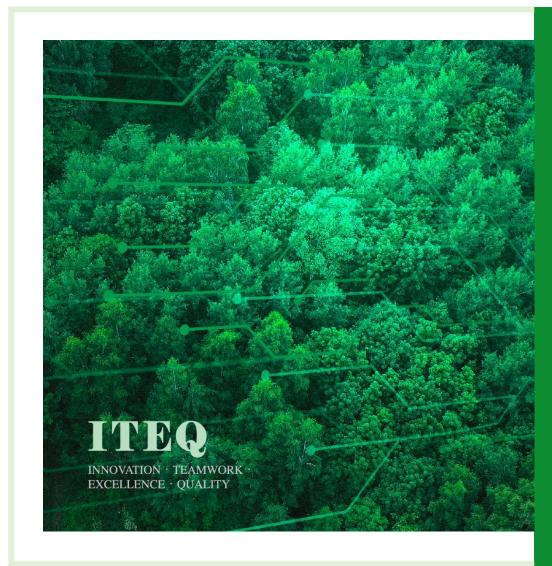


Disclaimer Statement

- This presentation and release contain "forward-looking statements" which may include projections of future results of operations, financial condition or business prospects based on our own information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.





Company Overview



Establishment April 10th, 1997



Headquarters HsinChu, Taiwan



Capital NT\$3,830 million



Employees ~4,000



Chairman
Dennis Chen



CEO Audrey Tsai



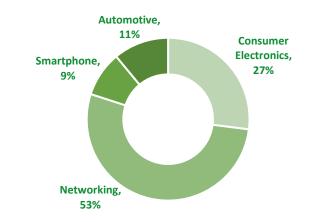
Main Products

Copper Clad Laminate (CCL) & Prepreg (PP) | Masslam service | Flexible CCL

Revenue (NT\$ billion)



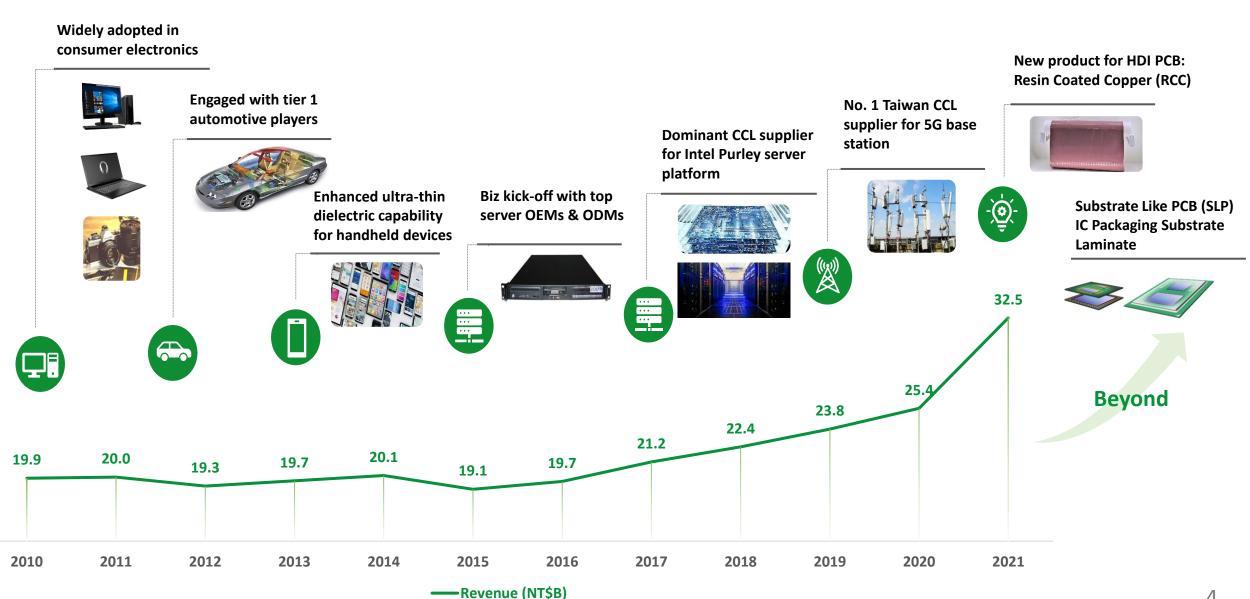
Revenue by Application (FY21)



3

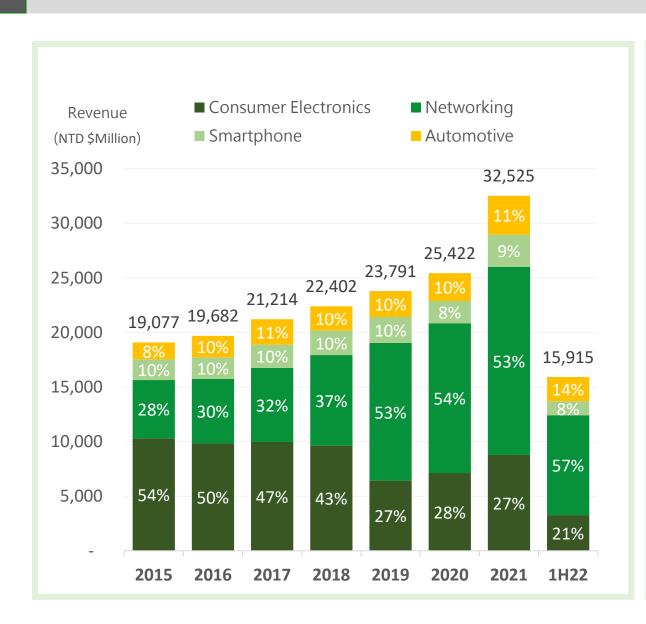
Revenue Growth Driven by Technology Innovation

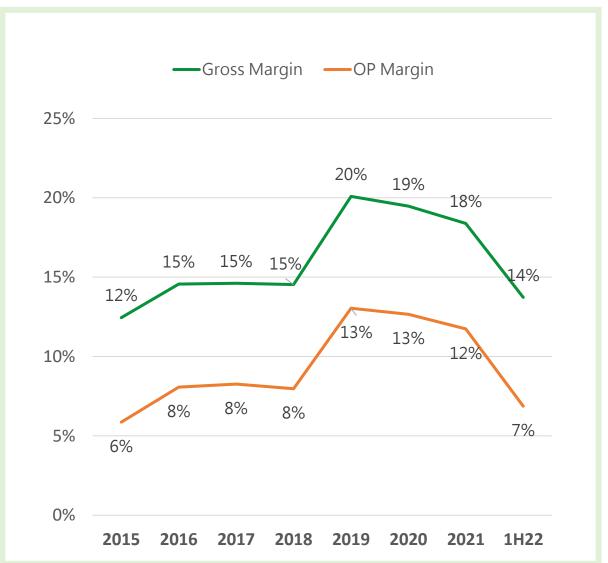




Improve Profitability through Optimized Product Mix

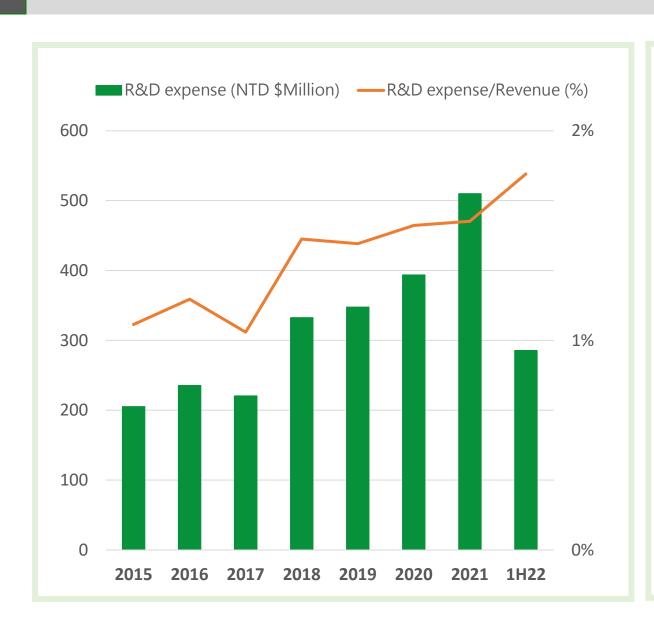


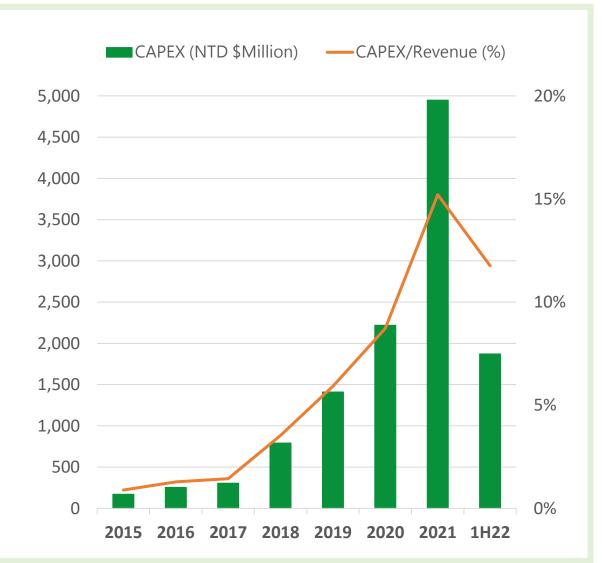




R&D and Capex to Pursuit Sustainable Growth



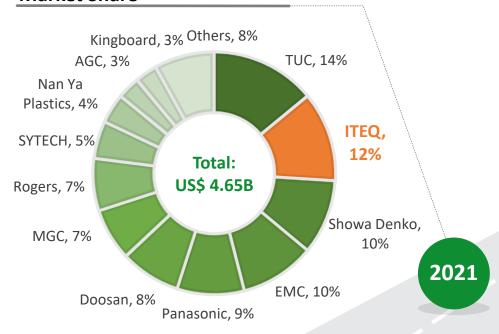




Our Goal - From a Leader to Global No.1



2021 Worldwide Specialty Laminate*
Market Share



*Specialty Laminate includes: High speed, package substrate, and RF Source: Prismark Report, 2022/05 **No.1** High Speed Materials & Specialty Laminate Supplier in the World by the End of **2025**

Growth Momentum

- Favorable Industry Trends
- Continuous High-end Products Development
- Strategic Layout of BT Substrate Materials
- Production Gearing Up



Sustainable Management of Future



Sustainlytics ESG Rating

(100-0, 0 being the best)

16.7 (Low Risk)

Board Structure

Independent Directors



Female Directors



Information Security

- Established "Cybersecurity & Data Privacy Committee"
- Reinforce ISMS (system, procedure, software/hardware upgrade, employee awareness) to ensure corporate & customer information asset security

Supply Chain Management & Customer Service

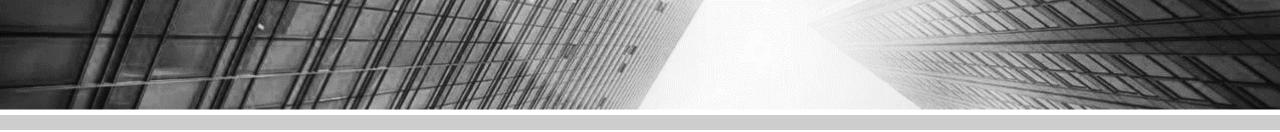
- Supplier Risk Management: 58
 vendors participated in the RBA
 audit and evaluation, with a
 100% completion rate in 2021
- Customer Survey: Level A
 rating according to the 2021
 customer satisfaction survey

Environmental Management

- Heat recovery by RTO in TW plant's carbon reduction measures and air pollution elimination rate >96%
- Implemented ISO 50001 Energy
 Management System in TW plant
- >99% Wastewater recovery ratein TW plant

Occupational Health & Safety

- Qualification of Occupational Health and Safety Management System of ISO 45001.
- Total of 132 members of the Occupational Health and Safety Committee; with 75 representatives of labor workers, higher than the ratio of regulation requirement.



Industry Trend & Growth Momentum

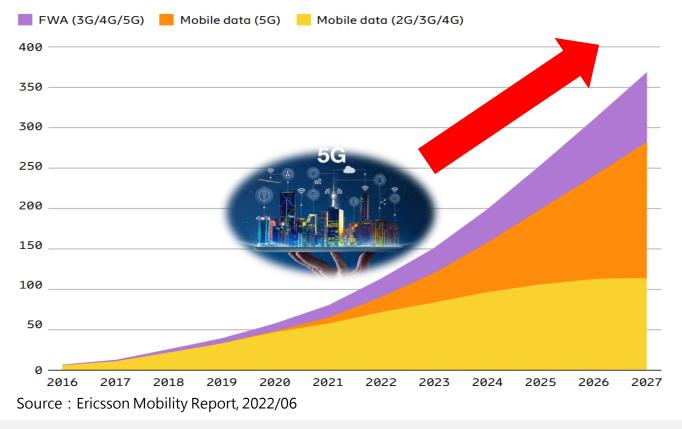




Industry Trend – Rising Demand of High-Speed / Frequency Transmission



Global Mobile Network Data Traffic (EB per month)



- The Expansion of Global Mobile Network Data Traffic Continues on the Rise
- Telecommunications equipment & datacenter
 - Base station, ground satellite transceiver station
 - Core (traditional / cloud datacenter)
 - Edge computing (Enterprise enhanced infrastructure, such as data center & internal/external servers, signal transmission stations, etc.)
- End user products (computers, smartphones, IoT devices)
- IoT related applications (Smart Home & Telemedicine)
- Internet of Vehicles (ADAS & Self-Driving)
- Big Data Analysis & Al & High Performance Computing
- Cloud Computing and Cloud Storage
- Virtual Reality (VR) and Augmented Reality (AR)

- 5G mobile data traffic share to reach 60% in 2027.
- The expansion of global mobile network data traffic has driven network service operators, telecommunications companies and IoT & IoV manufacturers to expand/upgrade product specifications to meet the needs of low latency, high reliability and high-speed computing processing

Well Diversified High-Speed Materials for HPC/Datacenter



High Speed Application

Tilgii Speed Application					
Super Ultra Low-loss	IT-999G IT-998G	IT-998 / IT-998SE	Next IT-998SE: Low-Dk glass IT-998: Low-Dk 2 glass	- 800G Ethernet - 112Gbps	0.001
Ultra Low-loss 2 (with Low Dk glass)	IT-988GSE IT-968GSE	IT-968SE	Intel EGS / BHS AMD Genoa / Turin	PCIe 5.0200G Ethernet400G Ethernet56Gbps	0.002 0.003
Ultra Low-loss 1 Low-loss Advance	IT-988G IT-968G	IT-968	Intel EGS / BHS AMD Genoa / Turin	- PCle 5.0 - 100G Ethernet - 25~32Gbps	0.004 0.00 0.00 0.00 Df @10GHz (RC 50%)
<u>Low-loss</u>	IT-958G IT-170GRA2	IT-150DA	Intel Whitley AMD Rome / Milan	- PCIe 4.0 - 40G Ethernet - 10~20Gbps	0.007 O.007
Mid-loss	IT-170GRA1		Intel Purley AMD Naples	- PCle 3.0	0.009
Loss Level	Halogen Free	Halogenated	Platform	Application	11

Datacenter Server Platform Upgrade



	Platform CPU		Purley		Eagle Stream		Birch Stream
			Cascade Lake	Ice lake	Sapphire Rapids	Emerald Rapids	Granite Rapids
	Nano Process	14 nm	14 nm+	10 nm	Intel 7	Intel 7	Intel 3
Intel	PCle Gen	PCle 3.0	PCle 3.0	PCIe 4.0	PCIe 5.0	PCle 5.0	TBA
	MP Time	2017 Q3	2019 Q3	2021 Q1	2023 H1	2023	2024
	CCL Material	Mid Loss	Mid Loss	Low Loss	Very Low Loss	Very Low Loss	TBD
	Layer count	8 to 12	8 to 12	12 to 16	16 to 20	16 to 20	TBD





	Architecture	Zen	Zen2	Zen3	Zei	n4	Zen5
	CPU	Naples	Rome	Milan	Genoa	Bergamo	Turin
	Nano Process	14 nm (Global Foundries)	7 nm (TSMC)	7 nm (TSMC)	5 nm (TSMC)	5 nm (TSMC)	3 nm (TSMC)
AMD	PCle Gen	PCle 3.0	PCIe 4.0	PCIe 4.0	PCle 5.0	PCle 5.0	PCle 5.0
	MP Time	2017 Q3	2019 Q3	2020 Q4	2022 Q4	2023	2024
	CCL Material	Mid Loss	Low Loss	Low Loss	Very Low Loss	Very Low Loss	TBD
	Layer count	8 to 12	12 to 16	12 to 16	16 to 20	16 to 20	TBD

Datacenter Equipment Cyclical Upgrade to Drive the Following;

- Corresponding CCL material upgrade
- Increase consumption and layer counts for CCL

Advanced Auto Application Opportunities



Green Power/EV



- Energy Conservation
- Power Charging
- High Current & Voltage
- Heavy Cu

High Tg material

Internet of Vehicle

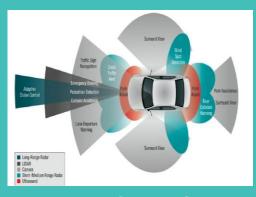


- Infotainment
- Networking

HDI

High Speed Material

Active Safety



- Active Safety System
- ADAS
- Radar
- Antenna Module

High Speed Material

High Frequency Material

Autonomous Driving



- HPC
- Graphic Processing
- Automated Driving Control Module

HDI

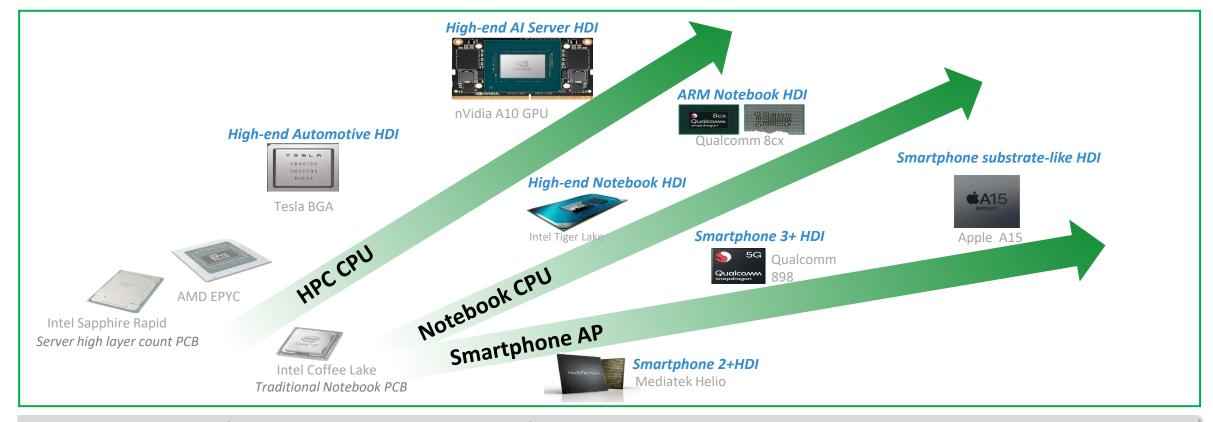
High Speed Material

- EV, IoV and Active Safety to boost demand for high performance automotive CCL
- The PCB usage for EV is 3 folds of conventional gasoline vehicles
- With the accelerating EV proliferation, global EV penetration rate is expected to reach 21% and 45% in 2025 and 2030, respectively.

Evolution of Computing Chips to Drive HDI Demand



• The organic growth of transistor numbers in main chip and miniature of CPU/AP, coupled with advanced packaging development while maintaining the same size of the end products, will lead to HDI PCB uptrend inevitably



- The evolution of chips will drive the growth of HDI PCB.
- Though HDI demand mainly came from smartphone; but AI servers, high-end NB and NEV will also continue
 to drive the future demand of HDI.

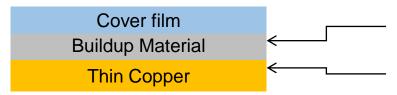
New Product: Resin Coated Copper (RCC)

enhanced reliability of signal transmission



Resin Coated Copper (RCC)

✓ Glass-free solution which enables further thickness reduction of dielectric layer while satisfies the needs towards fine-line pattern design and hybrid HDI/Substrate-Like PCB production.

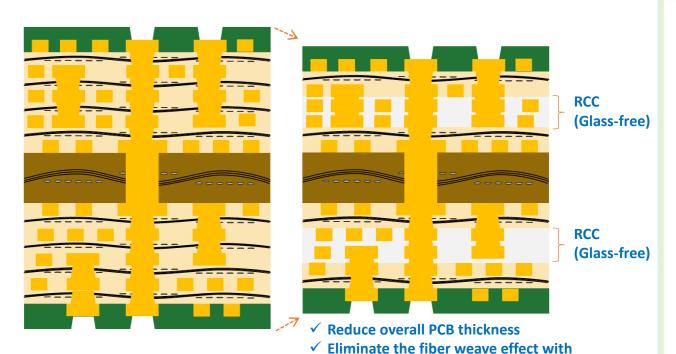


Dielectric Layer: 10~50um

X Available for thickness up to 150um

Conductors: Copper Foil





ITEQ RCC Advantages

Glass-Free

Reduce thickness of the dielectric layer and overcome minimum thickness constraints (15-20um)

Reduce Material Costs

Copper foil + glass fiber + resin \rightarrow Copper foil + resin; replace traditional stacking

Simplify PCB Lamination process

Combine the processes of PP/Copper foil stack-up into one

Better Dielectric Constant (Dk) and Impedance Control

RCC uses pure glue material enabling stable dielectric constant

Better Laser Processability

RCC is a glass fiber free material, which is easier to form holes through laser drilling with more stable Via quality

New Business: IC Substrate Material



MGC IC Packaging Laminate MGC & ITEQ JV

IC Substrate Material ITEQ
High-speed /
frequency CCL









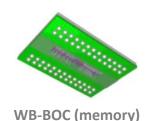


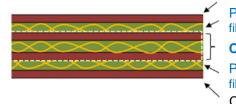


BT Substrate (ITEQ x MGC JV)









Copper foil
Prepreg (BT resin+ Glass

Core (BT resin based)

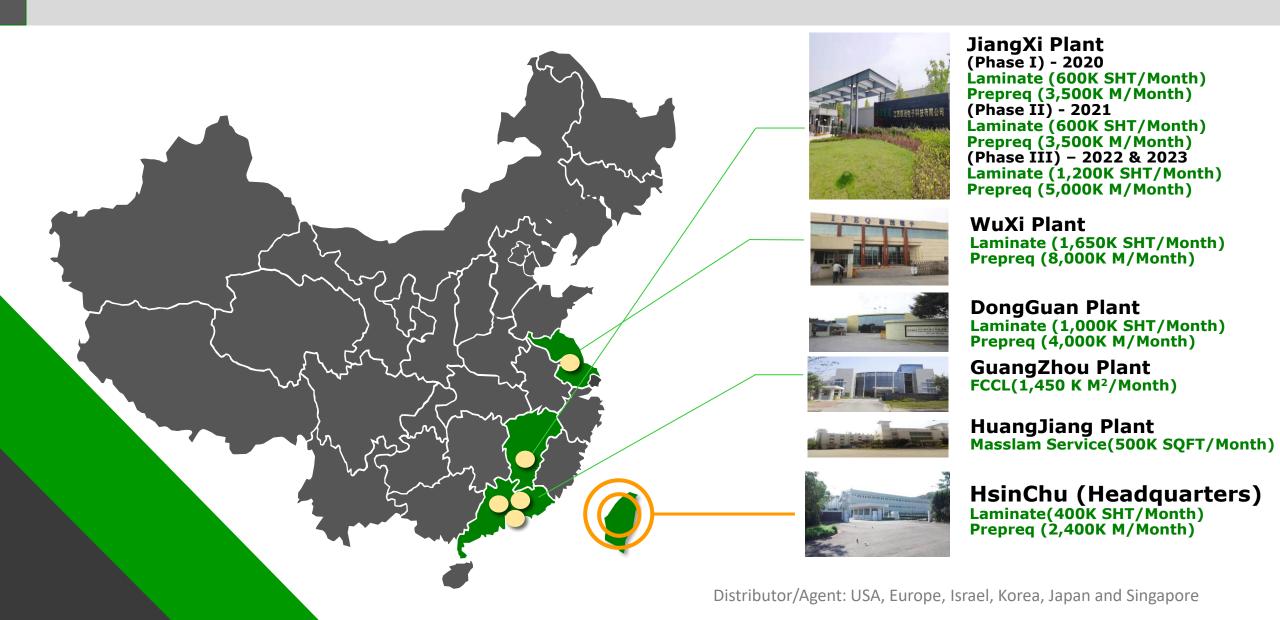
Prepreg (BT resin+ Glass fiber)

Copper foil

WB-CSP / PBGA

Manufacturing Site & Capacity – Expansion Plan







2Q22 & 1H22 Financial Results





2Q22 & 1H22 Income Statement

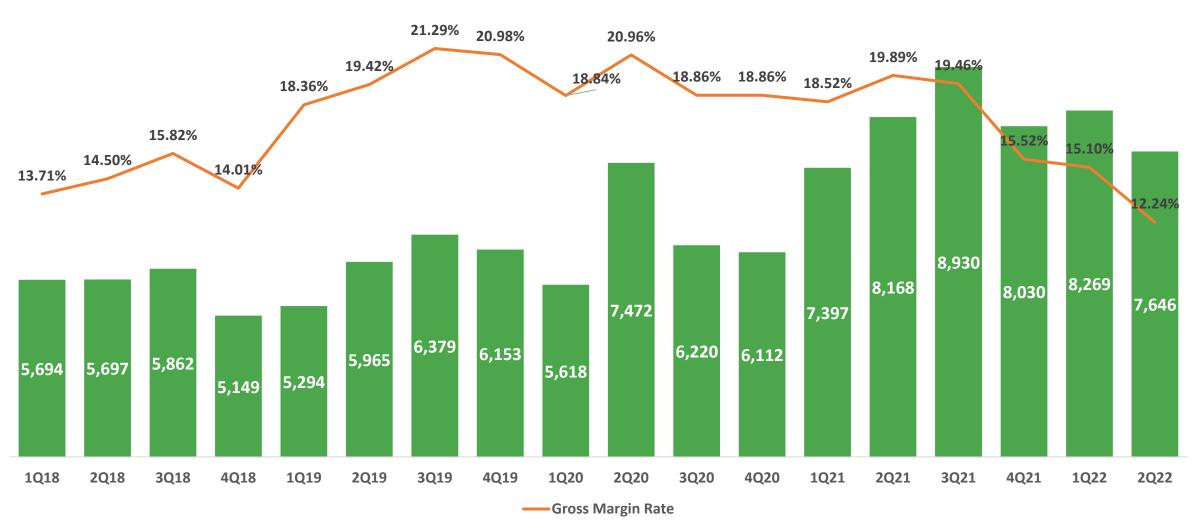


NTD \$Million	2Q22	1Q22	2Q21	QoQ	YoY	1H22	1H21	YoY
Revenue	7,646	8,269	8,168	-7.5%	-6.4%	15,915	15,564	2.3%
Gross Profit	936	1,249	1,625	-25.1%	-42.4%	2,185	2,995	-27.1%
Operating Expense	486	605	483	-19.7%	0.6%	1,091	987	10.6%
Operating Profit	450	644	1,142	-30.1%	-60.6%	1,094	2,009	-45.6%
Non-Op Income / Loss	146	332	(19)			478	(43)	
Income before Tax	596	976	1,123	-38.9%	-46.9%	1,572	1,965	-20.0%
Tax Expense	161	167	263			328	463	
Net Income to Parent	435	809	860	-46.2%	-49.4%	1,244	1,502	-17.2%
EPS(NT\$)	1.14	2.11	2.58	-46.0%	-55.8%	3.25	4.51	-27.9%
Key Financial Ratio						 		
Gross Margin	12.24%	15.10%	19.90%			13.73%	19.25%	
Operating Expense Ratio	6.36%	7.32%	5.92%			6.86%	6.34%	
Operating Margin	5.89%	7.79%	13.98%			6.87%	12.91%	
Effective Tax Rate	27.01%	17.11%	23.42%			20.88%	23.56%	
Net Margin	5.69%	9.78%	10.53%			7.82%	9.65%	

Revenue & Gross Margin Rate



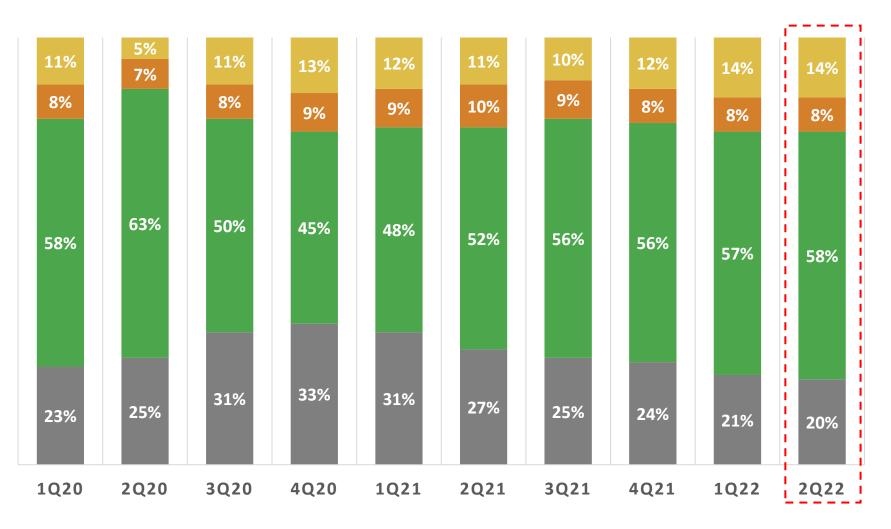
(Million \$NTD)



1Q20~2Q22 Product Mix







2Q22 Growth rate	QoQ	YoY	
Automotive	-7.5%	+31.1%	
Smartphone	-7.5%	-31.9%	
Networking	-5.9%	+4.4%	
Consumer Electronics	-11.9%	-30.7%	

2Q22 Balance Sheet



	r		
NTD \$Million	2Q22	1Q22	2Q21
Total Assets	34,043	35,614	32,698
Cash	3,873	3,711	2,749
Marketable Securities	4	5	5
NR / AR	13,799	14,377	13,403
Inventories	3,872	4,822	4,161
Fixed Assets	10,276	10,122	9,569
Total Liabilities	13,092	14,830	17,960
Short-term Debt	2,051	2,494	3,144
NP / AP	5,686	6,644	7,661
Long-term Debt		-	1,370
Total Equity	20,951	20,784	14,738
Key Financial Index			
Days Sales Outstanding	151	151	159
Days Sales of Inventory	64	69	64
Days Payable Outstanding	84	91	102
ROE (%)	13.60	15.73	20.80
ROA (%)	8.42	9.40	10.23
Debt ratio (%)	38.46	41.64	54.93
	Laboration		

2015 – 2021 Dividend Policy



Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2015	1.92	1.6	1.6	83%
2016	3.13	2.5	2.5	80%
2017	4.11	3.1	3.1	75%
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%
2020	8.19	5.0	5.0	61%
2021	9.00	5.0	5.0	56%

^{*}New shares issuance of 30 million common shares concluded on March 31st 2020

^{**}New shares issuance of 50 million common shares concluded on September 2nd 2021; current total outstanding common share: 383 million



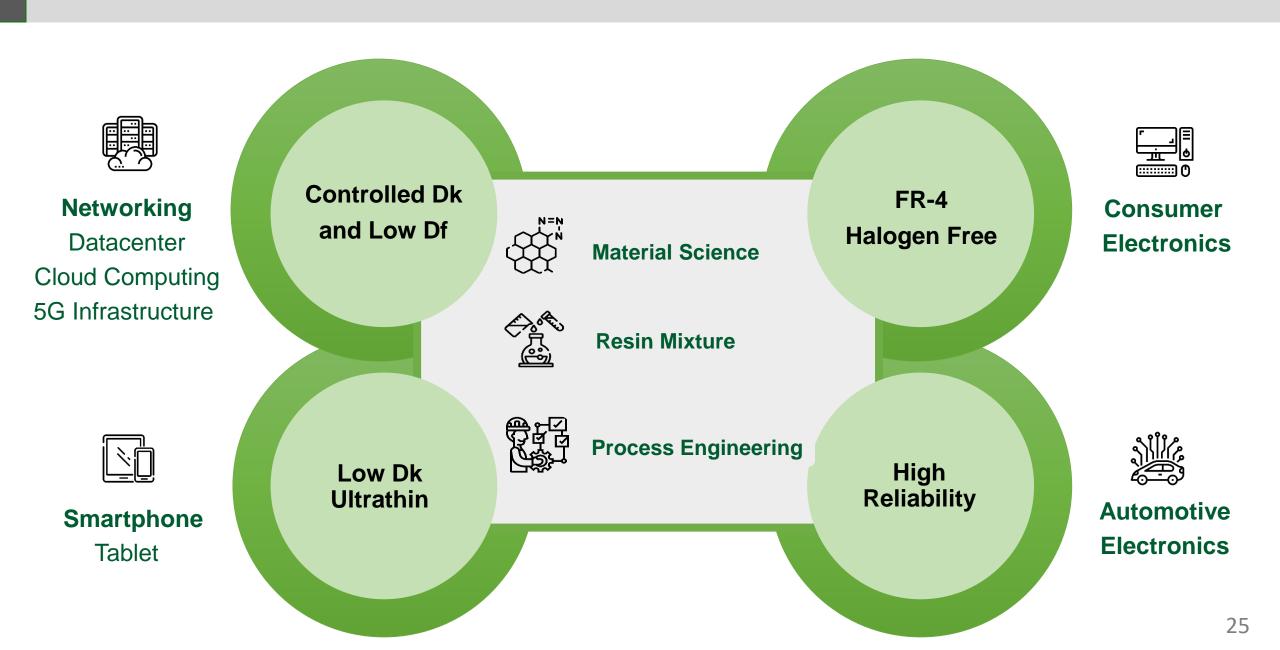
Appendix





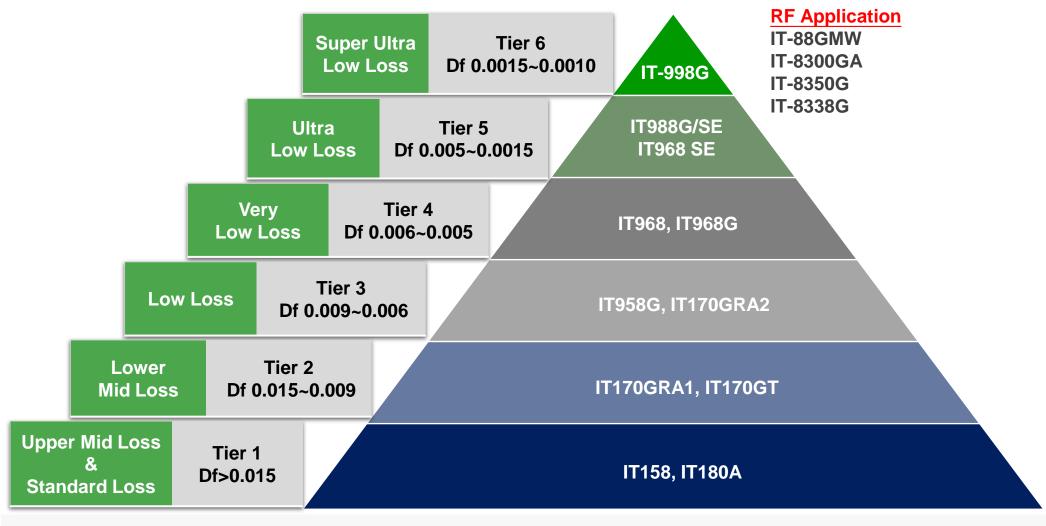
Key Technology Applications





Well-Expanded Product Line

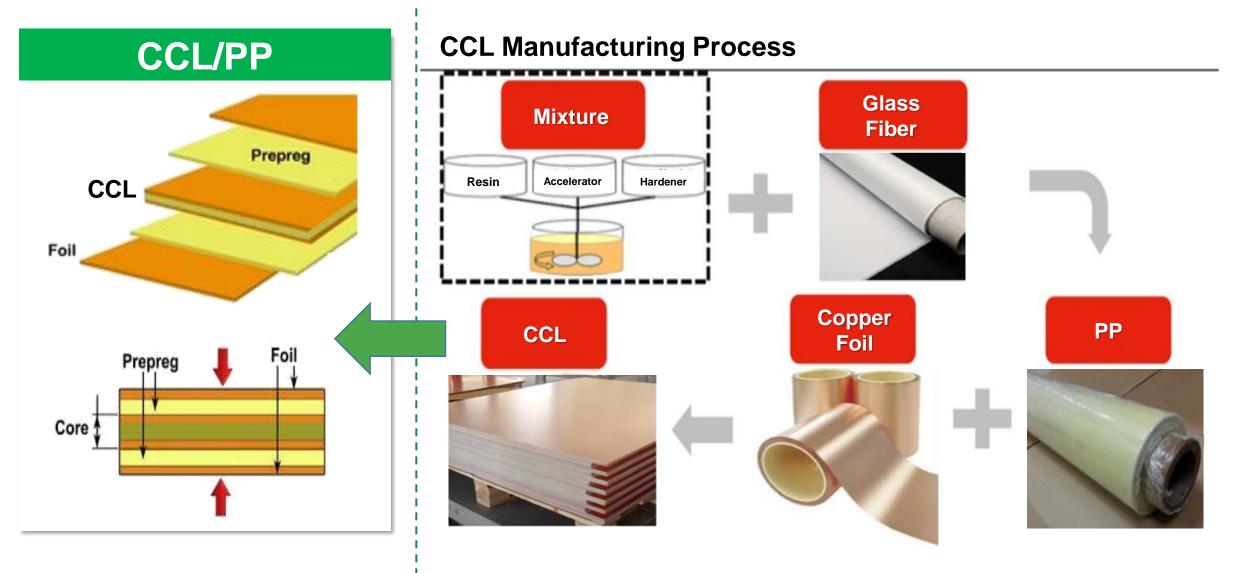




- The need for 5G commercialization and server upgrade to expedite the growth of high speed / frequency material demand
- ITEQ's market share in high speed / frequency material to uplift robustly

CCL & PP Composite Structure





CCL & PP Manufacturing Flow



